Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTION:**

1. **GND**
2. **INPUT +**
3. **INPUT +**
4. **V –**
5. **BAL**
6. **BAL/STROBE**
7. **OUTPUT V +**

****

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size: .003” x .004” min.**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .010” X .015” DATE: 6/1/22**

**MFG: SILICON SUPPLIES THICKNESS .007” P/N: SISH10**

#### Rev B, 7/19/02